| | | | | | · | |
|-----|-------|--|---|----|------|------------------|
| L12 | | 11 and 1 . | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/05 09:41 |
| L14 | 181 | 5 and (deposit\$5 near6 ((vapor adj deposition) or (cvd or pvd))) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/05 10:56 |
| L15 | 33 | 14 and ((wash\$5 or clean\$5) near7 (solder)) . | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/05 09:55 |
| L17 | 39 | 9 and (((vapor adj deposition) or (cvd or pvd))) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON · | 2005/09/05 10:16 |
| L18 | | 8 and ((solder) near7 ((vapor adj deposition) or (cvd or pvd))) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/05 11:23 |
| L20 | 1 | 9 and ((solder) with ((vapor adj deposition) or (cvd or pvd))) . | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/05 10:16 |
| L21 | 42100 | ((metal or metallic) near3 (stencil or mask or template or resist)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/05 10:56 |
| L22 | 57 | 21 and (solder\$5 near6 ((vapor adj deposition) or (cvd or pvd))) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/05 11:11 |
| L23 | 12 | 22 and (((oxidation or oxide) or (clean\$4 or wash\$4)) near7 (solder)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/05 11:12 |
| L24 | · 130 | ((((("0.5") near3 mil) or (("0.01" or "0.02") near2 (mm or millimeter)) or (("12" or "13") near2 (micron or "um"))) near5 (thick or thickness or height)) with (solder)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/05 11:23 |
| L25 | 3 | 24 and ((solder) near7 ((vapor adj deposition) or (cvd or pvd))) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/05 11:24 |

| L26 | 2 | ("4,772,935").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; | OR | OFF | 2005/09/05 11:24 |
|-----|----|--|---|----|-----|------------------|
| L27 | 57 | "228"/\$.cds. and (solder with (protect\$3 with time)) | IBM_TDB US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/05 12:03 |
| L28 | 57 | "228"/\$.ccls. and (solder with (protect\$4 with time)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/05 12:08 |
| L29 | 22 | "228"/\$.ccls. and (solder with (nitrogen) with (clean\$4 or wash\$4)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/05 12:03 |
| L30 | 10 | "228"/\$.ccls. and (solder with (protect\$4 with (storage or transportation))) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/05 12:13 |
| L31 | 3 | "29"/\$.ccls. and (solder with (protect\$4 with (storage or transportation))) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/05 12:13 |